OFFICE OF INDUSTRIAL LIAISON, PLACEMENTS & PRACTICE SCHOOL MIT, MANIPAL MTech 2019 - 2021

SI No.	NAME OF THE COMPANY		IT		Total	tal CTC	
			CNE	SWE			
1	Mercedes	P	1		1	7.5 LPA	
2	Dell Technologies	I2P	2	1	3	10 LPA	
3	Infineon	I2P	1	1	2	12.6 LPA + 1L bonus	
	Total		4	2	6		

	IT		Total
	CNE	SWE	
Single Job	4	2	6
Double Job			0
Triple Job			0
Four Jobs			0
Total	4	6	

Statistics of MTech students selected for Internship during the year 2018-19

C NI	ТҮРЕ	Name of the Company		IT	
3.N.	ITPE		CNE	SE	Stipend
	No. of Eligible students - 6CGPA & Above, no BL		17	15	
1	Core Engg.	Dell	4	2	25000 pm
2	Core Engg.	Intel	4		35000 pm
3	Core IT	Beckman Coulter	1	1	25000 pm
4	Core Engg.	Infineon	1	1	28333 pm
5	Core Engg.	Oracle - RGBU	1	2	26000 pm
6	Core Engg.	NXP Semiconductors	1		25000 pm
7	Core IT	Spirent Communications	1		25000 pm
8	Core Engg.	Nokia	2	1	30000 pm
9	Core IT	Fireeye		1	30000 pm
10	Core Engg.	Altair		1	20000 pm
11	Core IT	Mast Global		1	30000 pm
			15	10	

OFFICE OF INDUSTRIAL LIAISON, PLACEMENTS & PRACTICE SCHOOL MIT, MANIPAL Statistics of MTech Placements during the Year 2018-19

			IT					
	NAME OF THE COMPANY							
SI No.			CNE	SWE	стс			
31110.	Batch size			4				
	Eligible students		9	3				
1	Dell	Р		1	10 LPA			
	ben	I2P	1		10 1111			
2	Cerner Corporation	Р	1		6.1 LPA			
2		I2P	1		0.1 LI A			
3	Arris	I2P	1		7 LPA			
4	VMWare	I2P		1	NA			
5	EFI	I2P	1		NA			
	Total		5	2				

	MIT, Manipal : PG : 2019 - 2020 Internship details						
C N	TYPE	Name of the Company		Т			
3.N.	ТҮРЕ			SE	Stipend		
	No. of Eligible students - 6CGPA & Above, no BL		8	10			
1	Core IT	Marvell	1		30000 pm		
2	Core Engg.	Dell	2	1	25000 pm		
3	Core Engg.	Infineon	1	1	36000 pm		
4	Core Engg.	Intel	1	1	40000 pm		
5	Core Engg.	Philips India Bangalore	1		25000 pm		
6	Core IT	Reliance Industries		1	50000 pm		
7	Core Engg	Signify		1	25000 pm		
8	Core Engg.	Nokia		1	30000 pm		
9	Core Engg.	Bosch		1	20000 pm		
10	Core Engg.	Spirent Communications		1	25000 pm		
		Total	6	8			

OFFICE OF INDUSTRIAL LIAISON, PLACEMENTS & PRACTICE SCHOOL MIT, MANIPAL

MTech Placement Details: 2019 - 2020

	NAME OF THE COMPANY		Date of Visit	IT				
SI No.					SWE	стс		
31 100.	Batch size			18	17	Cic		
	Eligible students				15			
1	Spirent Communications	I2P	30th April 2020	1		7.75 LPA		
2	Dell Technologies	I2P	8th May 2020	3	1	10 LPA		
3	Infineon	I2P	Mail received on 5th November, 2020	1	1	11.6 LPA		
	Total			5	2			